

ABSTRACT

5 A polishing apparatus capable of monitoring a distribution of an amount of liquid,
such as a polishing liquid or a chemical liquid, on a polishing surface of a polishing pad, and
capable of polishing an object, such as a wafer, under appropriate polishing conditions.
The polishing apparatus includes: a polishing table configured to support a polishing pad; a
polishing head configured to press the object against a polishing surface of the polishing pad;
10 a liquid supply device configured to supply liquid onto the polishing surface; a liquid
monitoring device configured to obtain optical information contained in light from a
plurality of points on the polishing surface; an optical information analyzer configured to
determine a distribution of amount of the liquid on the polishing surface from the optical
information; and an operation controller configured to control operations of the polishing
15 apparatus.

FIG. 1